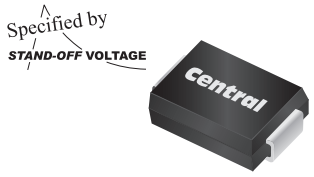
3SMC5.0CA
THRU
3SMC170CA

SURFACE MOUNT SILICON
BI-DIRECTIONAL
GLASS PASSIVATED JUNCTION
TRANSIENT VOLTAGE SUPPRESSORS
3000 WATT, 5.0 THRU 170 VOLT



SMC CASE

Central Semiconductor Corp.

www.centralsemi.com

DESCRIPTION:

The CENTRAL SEMICONDUCTOR 3SMC5.0CA series devices are surface mount bi-directional glass passivated junction Transient Voltage Suppressors designed to protect voltage sensitive components from high voltage transients.

THIS DEVICE IS MANUFACTURED WITH A GLASS PASSIVATED CHIP FOR OPTIMUM RELIABILITY.

Note: For uni-directional devices, please refer to the 3SMC5.0A series data sheet.

MARKING CODE: SEE MARKING CODE ON ELECTRICAL CHARACTERISTIC TABLE

MAXIMUM RATINGS: (T_A=25°C unless otherwise noted)	**SYMBOL**		**UNITS**
Peak Power Dissipation (Note 1)	P_{PK}	3000	W
Operating and Storage Junction Temperature	T_J, T_{stg}	-65 to +150	°C

ELECTRICAL CHARACTERISTICS: (T_A=25°C unless otherwise noted)

TYPE	REVERSE STAND-OFF VOLTAGE V_{RWM}	BREAKDOWN VOLTAGE V_{BR} @ I_T		TEST CURRENT I_T	MAXIMUM REVERSE LEAKAGE CURRENT I_R @ V_{RWM}	MAXIMUM CLAMPING VOLTAGE V_C @ I_{PP}	PEAK PULSE CURRENT (Note 1) I_{PP}	MARKING CODE
	V	MIN V	MAX V	mA	µA	V	A	
3SMC5.0CA	5.0	6.40	7.25	10	2000	9.2	326.0	CIDE
3SMC6.0CA	6.0	6.67	7.67	10	2000	10.3	291.3	CIDG
3SMC6.5CA	6.5	7.22	8.30	10	1000	11.2	267.9	CIDK
3SMC7.0CA	7.0	7.78	8.95	10	400	12.0	250.0	CIDM
3SMC7.5CA	7.5	8.33	9.58	1.0	200	12.9	232.6	CIDP
3SMC8.0CA	8.0	8.89	10.23	1.0	100	13.6	220.6	CIDR
3SMC8.5CA	8.5	9.44	10.82	1.0	50	14.4	208.4	CIDT
3SMC9.0CA	9.0	10.0	11.5	1.0	20	15.4	194.8	CIDV
3SMC10CA	10	11.1	12.8	1.0	5.0	17.0	176.4	CIDXS
3SMC11CA	11	12.2	14.0	1.0	5.0	18.2	184.8	CIDZ
3SMC12CA	12	13.3	15.3	1.0	5.0	19.9	150.6	CIEE
3SMC13CA	13	14.4	16.5	1.0	5.0	21.5	139.4	CIEG
3SMC14CA	14	15.6	17.9	1.0	5.0	23.2	129.4	CIEK
3SMC15CA	15	16.7	19.2	1.0	5.0	24.4	123.0	CIEM
3SMC16CA	16	17.8	20.5	1.0	5.0	26.0	115.4	CIEP
3SMC17CA	17	18.9	21.7	1.0	5.0	27.6	106.6	CIER
3SMC18CA	18	20.0	23.3	1.0	5.0	29.2	102.8	CIET
3SMC20CA	20	22.2	25.5	1.0	5.0	32.4	92.6	CIEV
3SMC22CA	22	24.4	28.0	1.0	5.0	35.5	84.4	CIEX
3SMC24CA	24	26.7	30.7	1.0	5.0	38.9	77.2	CIEZ
3SMC26CA	26	28.9	33.2	1.0	5.0	42.1	71.2	CIFE
3SMC28CA	28	31.1	35.8	1.0	5.0	45.4	66.0	CIFG
3SMC30CA	30	33.3	38.3	1.0	5.0	48.4	62.0	CIFK

Note 1: Non-repetitive 10x1,000µs pulse.

R12 (17-March 2016)

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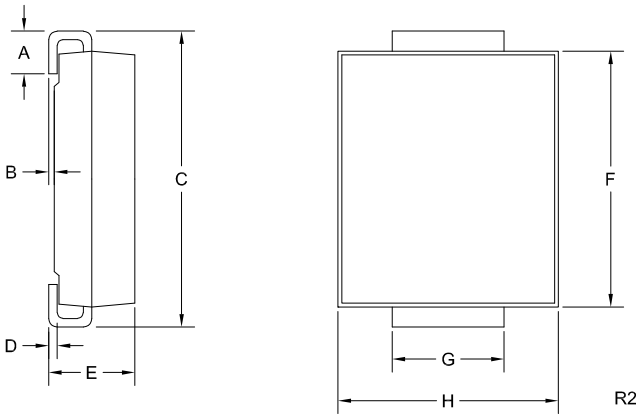
ELECTRICAL CHARACTERISTICS - Continued: (T_A=25°C unless otherwise noted)

TYPE	REVERSE STAND-OFF VOLTAGE V_{RWM}	BREAKDOWN VOLTAGE V_{BR} @ I_T		TEST CURRENT I_T	MAXIMUM REVERSE LEAKAGE CURRENT I_R @ V_{RWM}	MAXIMUM CLAMPING VOLTAGE V_C @ I_{PP}	PEAK PULSE CURRENT (Note 1) I_{PP}	MARKING CODE
	V	MIN V	MAX V	mA	µA	V	A	
3SMC33CA	33	36.7	42.2	1.0	5.0	53.3	56.2	CIFM
3SMC36CA	36	40.0	46.0	1.0	5.0	58.1	51.6	CIFP
3SMC40CA	40	44.4	51.1	1.0	5.0	64.5	46.4	CIFR
3SMC43CA	43	47.8	54.9	1.0	5.0	69.4	43.2	CIFT
3SMC45CA	45	50.0	57.5	1.0	5.0	72.7	41.2	CIFV
3SMC48CA	48	53.3	61.3	1.0	5.0	77.4	38.8	CIFX
3SMC51CA	51	56.7	65.2	1.0	5.0	82.4	36.4	CIFZ
3SMC54CA	54	60.0	69.0	1.0	5.0	87.1	34.4	CIGE
3SMC58CA	58	64.4	74.1	1.0	5.0	93.6	32.0	CIGG
3SMC60CA	60	66.7	76.7	1.0	5.0	96.8	31.0	CIGK
3SMC64CA	64	71.1	81.8	1.0	5.0	103	29.2	CIGM
3SMC70CA	70	77.8	89.5	1.0	5.0	113	26.6	CIGP
3SMC75CA	75	83.3	95.8	1.0	5.0	121	24.8	CIGR
3SMC78CA	78	86.7	99.7	1.0	5.0	126	22.8	CIGT
3SMC85CA	85	94.4	108.2	1.0	5.0	137	20.8	CIGV
3SMC90CA	90	100.0	115.5	1.0	5.0	146	20.6	CIGX
3SMC100CA	100	111.0	128.0	1.0	5.0	162	18.6	CIGZ
3SMC110CA	110	122.0	140.5	1.0	5.0	177	16.8	CIHE
3SMC120CA	120	133.0	153.0	1.0	5.0	193	15.6	CIHG
3SMC130CA	130	144.0	165.5	1.0	5.0	209	14.4	CIHK
3SMC150CA	150	167.0	192.5	1.0	5.0	243	12.4	CIHM
3SMC160CA	160	178.0	205.0	1.0	5.0	259	11.6	CIHP
3SMC170CA	170	189.0	217.5	1.0	5.0	275	11.0	CIHR

SMC CASE - MECHANICAL OUTLINE



DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.030	0.060	0.76	1.52
B	0.002	0.008	0.05	0.20
C	0.305	0.320	7.75	8.13
D	0.006	0.012	0.15	0.31
E	0.079	0.103	2.00	2.62
F	0.260	0.280	6.60	7.11
G	0.108	0.128	2.75	3.25
H	0.220	0.245	5.59	6.22

SMC (REV: R2)

R12 (17-March 2016)

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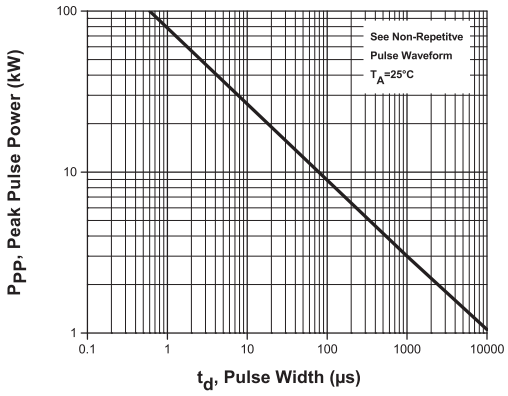
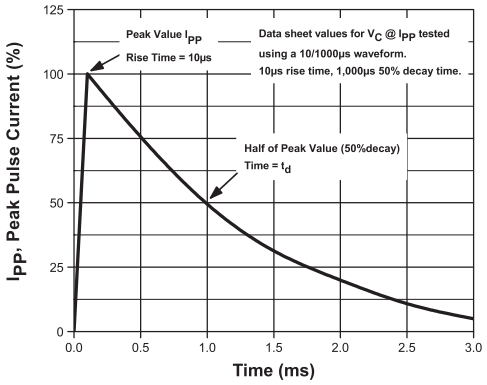
TYPICAL ELECTRICAL CHARACTERISTICS

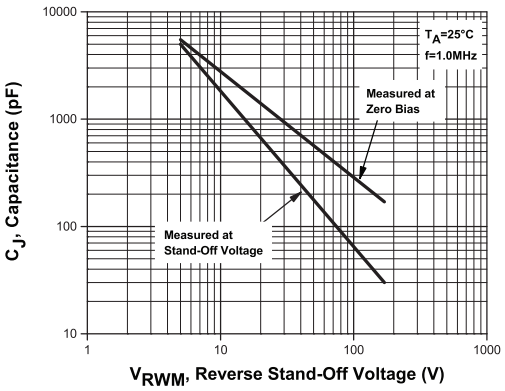
Peak Pulse Power



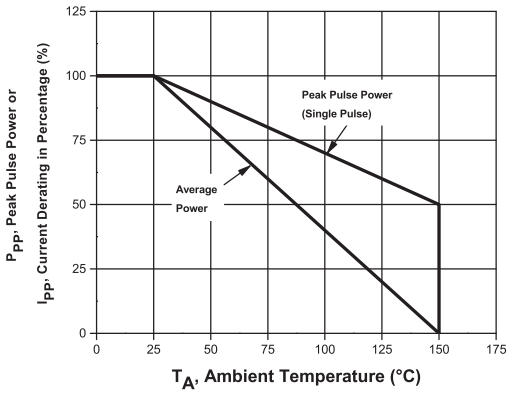
Non-Repetitive Pulse Waveform



Capacitance

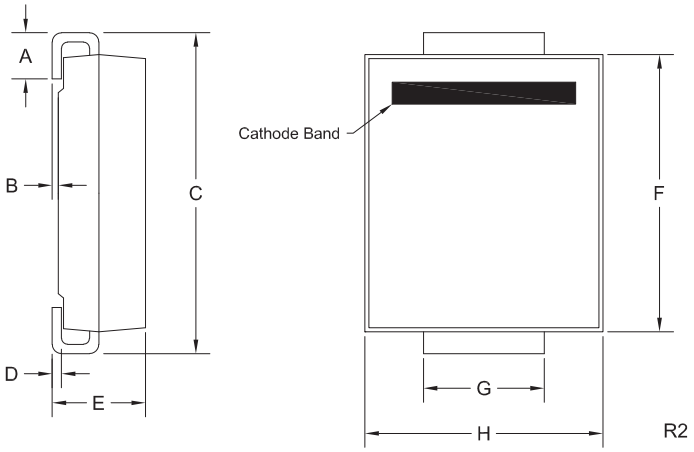


Power & Current Derating



Package Details
SMC Case

Mechanical Drawing



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	INCHES		MILLIMETERS	
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A	0.030	0.060	0.76	1.52
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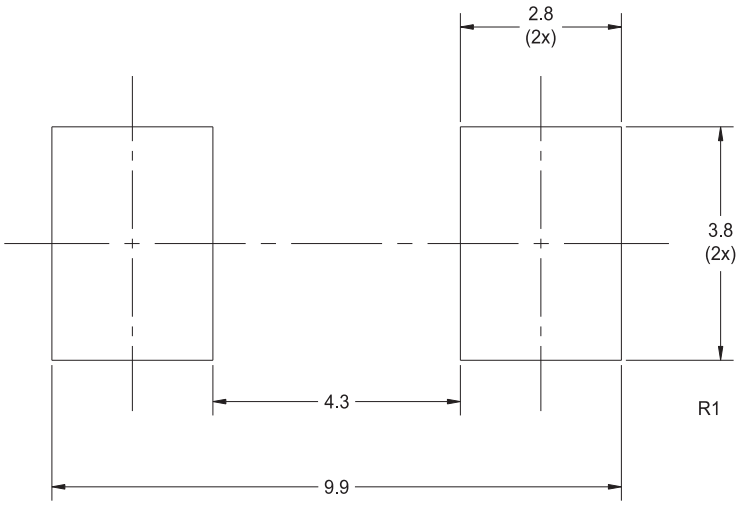
E	0.079	0.103	2.00	2.62
F	0.260	0.280	6.60	7.11
G	0.108	0.128	2.75	3.25
H	0.220	0.245	5.59	6.22

SMC (REV: R2)

Lead Code:
Reference individual device datasheet.

Part Marking: 3-6 Character Alpha/Numeric Code

Mounting Pad Geometry (Dimensions in mm)

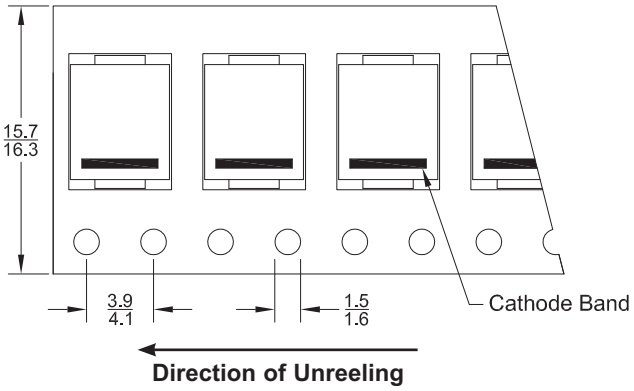


R4 (18-February 2021)

Package Details
SMC Case

Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 16mm



Devices are taped in accordance with Electronic Industries Association Standard EIA-481-D

Packaging Base

13” Reel = 3,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code and Ship Date.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
13”	4	12,000	15x4x15	38x10x38	12	6
	11	33,000	15x15x9	38x38x23	30	14
	24	72,000	15x15x18	38x38x46	64	29

Ordering Information

- For devices taped and reeled on 13” reels, add TR13 suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

Material Composition Specification

SMC Case

Device average mass . . . . . **232.5 mg**

Fluctuation margin . . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.63%	3.8	Si	7440-21-3	1.63%	3.8	16,344
leadframe	copper	39.11%	90.92	Cu	7440-50-8	39.11%	90.92	391,054
die attach	high temperature solder paste	1.88%	4.36	Pb	7439-92-1	1.73%	4.033	17,346
				Sn	7440-31-5	0.09%	0.218	938
				Ag	7440-22-4	0.05%	0.109	469
encapsulation*	EMC	56.77%	132	silica	7631-86-9	38.61%	89.76	386,065
				epoxy resin	29690-82-2	11.35%	26.4	113,548
				phenol resin	9003-35-4	5.68%	13.2	56,774
				Sb_2O_3	1309-64-4	0.57%	1.32	5,677
				Br	7726-95-6	0.57%	1.32	5,677
	EMC GREEN	56.77%	132	silica (fused)	60676-86-0	43.72%	101.64	437,161
				epoxy resin	29690-82-2	5.68%	13.2	56,774
				phenol resin	9003-35-4	5.51%	12.804	55,071
				carbon black	1333-86-4	0.17%	0.396	1,703
				metal hydroxide	1309-42-8	1.7%	3.96	17,032
plating**	tin/lead process	0.61%	1.42	Sn	7440-31-5	0.49%	1.136	4,886
				Pb	7439-92-1	0.12%	0.284	1,222
	matte tin	0.61%	1.42	Sn	7440-31-5	0.61%	1.42	6,108

*EMC GREEN molding compound is Halogen-Free.

**For Lead Free plating, add suffix “PB FREE” to part number.
For Tin/Lead plating, add suffix “TIN/LEAD” to part number.
No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

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